

## Features

- Low drain-source on-resistance:  $R_{DS(ON)}=0.34\Omega_{typ}$
- Easy to control gate switching
- Enhancement mode:  $V_{th} = 2$  to  $4V$
- 100% avalanche tested
- RoHS compliant

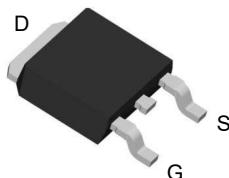
## Key Performance Parameters



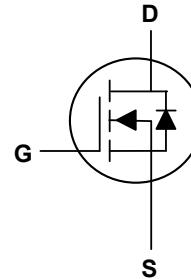
Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	650	V
$R_{DS(ON),max}$	380	$m\Omega$
$I_D$	13	A
$Q_{g,typ}$	19.5	nC
$I_{DM}$	45	A

## Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger, Lighting



TO-252 Top View



## Absolute Maximum Ratings( $T_c=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current <sup>1</sup>	$I_D$	13	A
Continuous Drain Current <sup>1</sup>	$I_D$	8.2	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	45	A
Single Pulse Avalanche Energy <sup>4</sup>	$E_{AS}$	163	mJ
Avalanche Current	$I_{AS}$	3.3	A
MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 400V$	dv/dt	50	V/ns
Reverse diode dv/dt <sup>3</sup> $V_{DS}=0 \dots 400V$ , $I_{SD} \leq I_D$		15	
Total Power Dissipation ( $T_c=25^\circ C$ )	$P_D$	105	W
Storage Temperature Range	$T_{STG}$	-55 to 150	°C
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	62	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	1.2	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	650	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$ , $I_D=6.5\text{A}$	---	340	380	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	2	---	4	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	100	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
Total Gate Charge	$Q_g$	$V_{\text{DD}}=400\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=6.5\text{A}$	---	19.5	---	nC
Gate-Source Charge	$Q_{\text{gs}}$		---	3.9	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	7.5	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=400\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=6.5\text{A}$	---	11.5	---	ns
Rise Time	$T_r$		---	23.5	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	43	---	
Fall Time	$T_f$		---	21.5	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	810	---	pF
Output Capacitance	$C_{\text{oss}}$		---	30	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	0.8	---	

**Drain-Source Diode Characteristics**

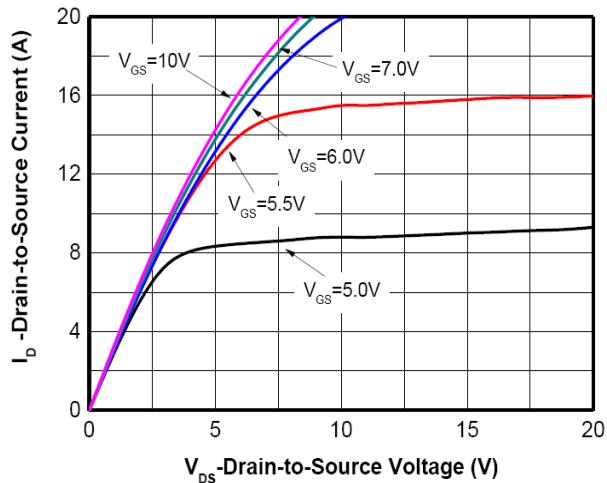
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current	$I_s$	$T_c=25^\circ\text{C}$	---	---	13	A
Pulsed Source Current	$I_{\text{SM}}$		---	---	45	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_G=0\text{V}$ , $I_s=13\text{A}$ , $T_J=25^\circ\text{C}$	---	0.9	1.4	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_{\text{DD}}=400\text{V}$ , $I_s=6.5\text{A}$ , $dI_F/dt=100\text{A}/\mu\text{s}$	---	250	---	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		---	1.8	---	$\mu\text{C}$
Peak Reverse Recovery Current	$I_{\text{rrm}}$		---	14.9	---	A

**Note:**

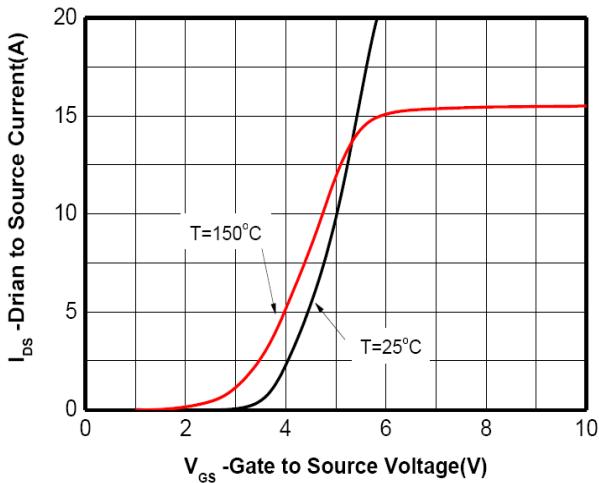
1. Limited by  $T_{j,\text{max}}$ . Maximum Duty Cycle D = 0.50
2. Pulse width  $t_p$  limited by  $T_{j,\text{max}}$
3. Identical low side and high side switch with identical  $R_G$
4.  $V_{\text{DD}}=50\text{V}$ ,  $R_G=25\Omega$

## Typical Characteristics

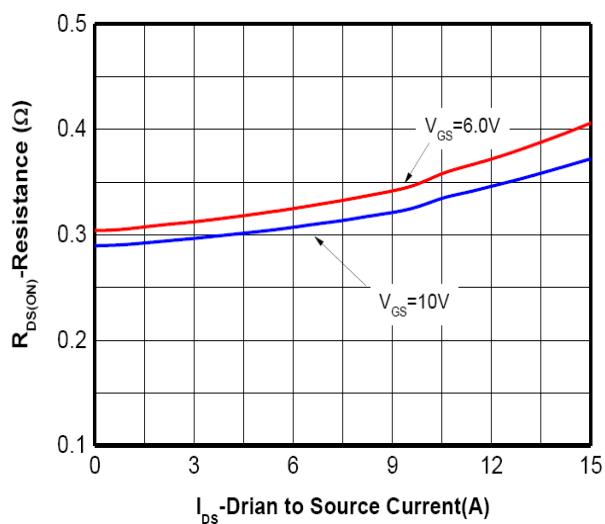
Typ. output characteristics  $T_f=25\text{ }^{\circ}\text{C}$



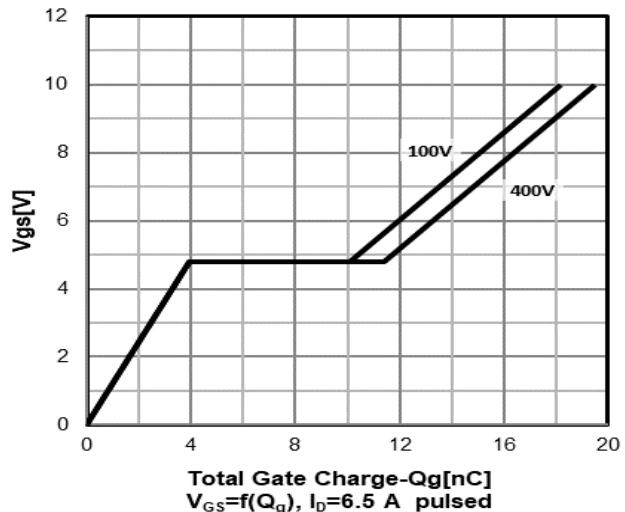
Typ. transfer characteristics



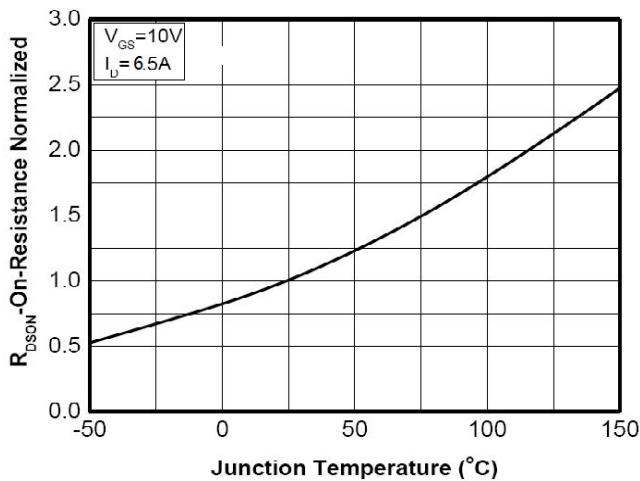
Typ. drain-source on-state resistance



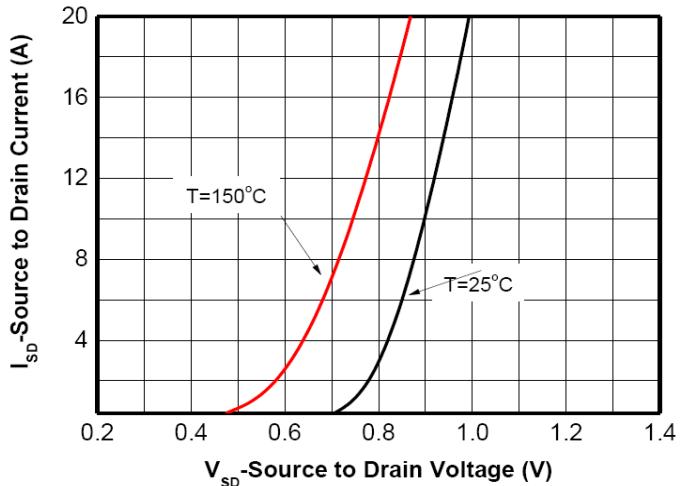
Typ. gate charge characteristics



Normalized on resistance vs temperature

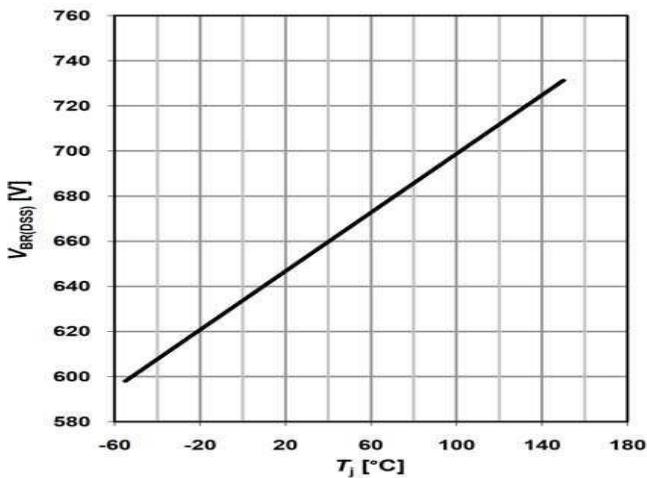


Forward characteristics of reverse diode

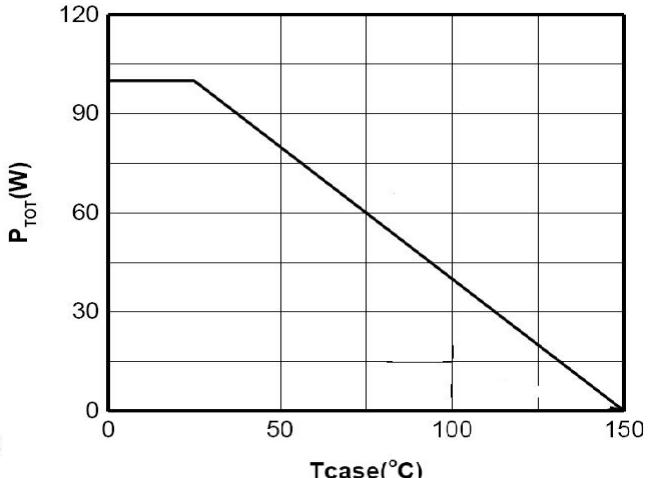


**650V Super Junction Power MOSFET**

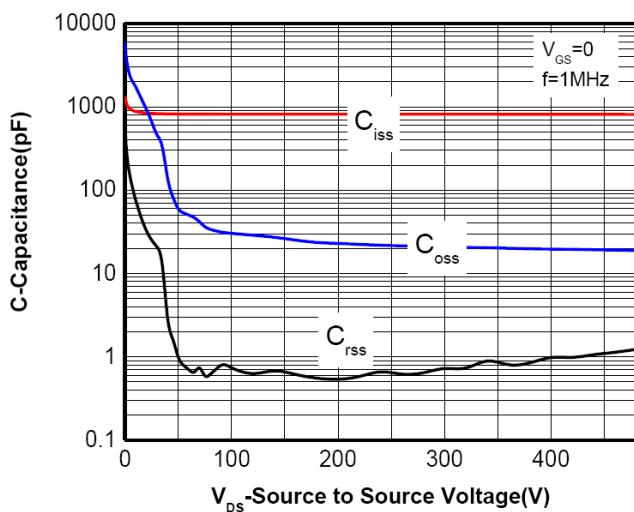
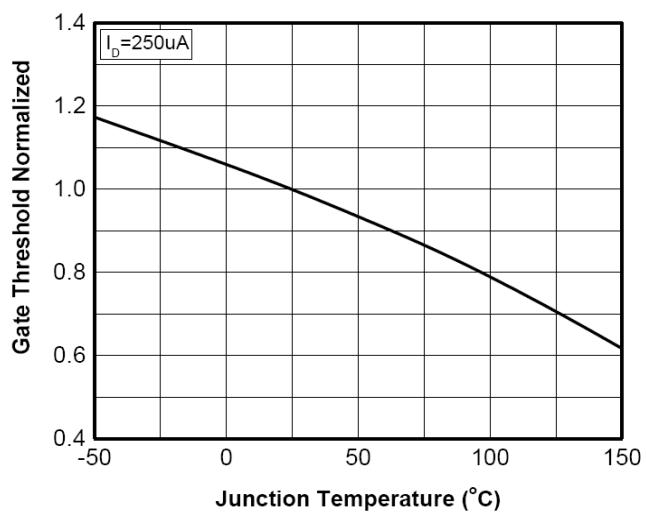
Drain-source breakdown voltage



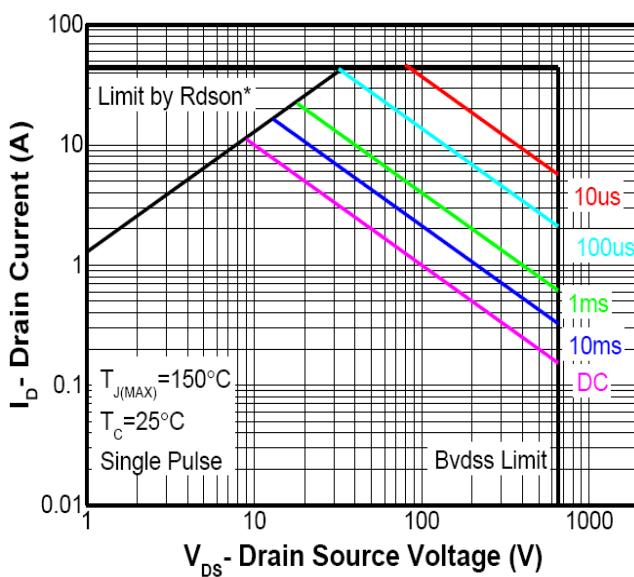
Power dissipation



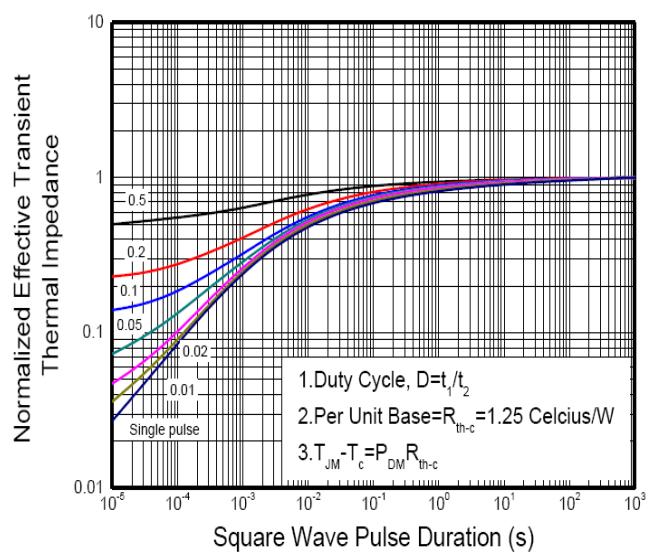
Typ. capacitances

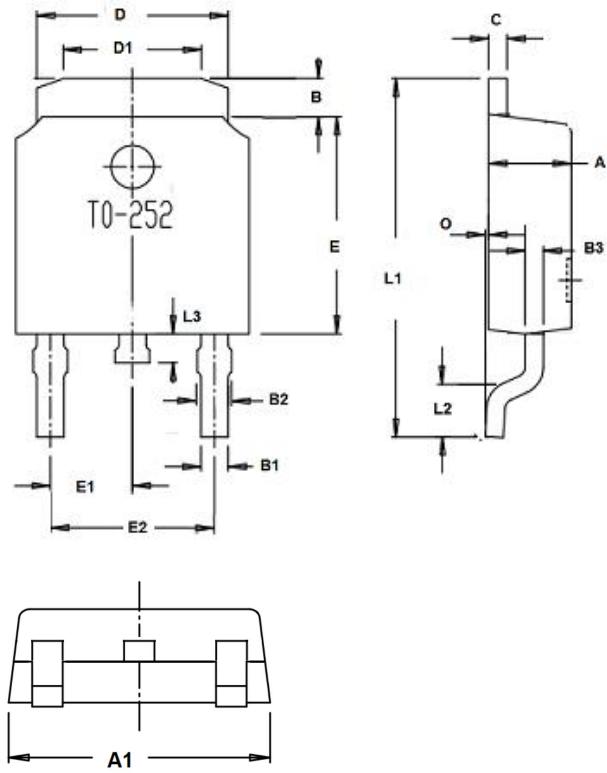

 Normalized V<sub>GS(th)</sub> characteristics


Safe operating area TC=25 °C



Max. transient thermal impedance



**TO-252 Package Outline Dimensions**

Dim.	Min.	Max.
A	2.1	2.5
A1	6.3	6.9
B	0.96	1.42
B1	0.74	0.86
B2	0.74	0.94
C	Typ0.5	
D	5.33	5.53
D1	3.65	4.05
E	6.0	6.2
E1	Typ2.29	
E2	Typ4.58	
O	0	0.15
L1	9.9	10.5
L2	Typ1.65	
L3	0.6	1.0
All Dimensions in millimeter		